

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: R. PENDSE, *et al.*

Application No.: 10/081,491

Filed: February 22, 2002

Title: Chip Scale Package with Flip Chip Interconnect



) Examiner: Angel ROMAN

) Group Art Unit: 2812

) Date: January 2, 2004

) CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 2, 2004.

Signed \_\_\_\_\_

  
Phil Kennedy

COMMISSIONER FOR PATENTS  
P. O. Box 1450  
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

Responsive to the Office Action mailed August 1, 2003; kindly amend the application as follows:

Amendments to the Claims are reflected in the **Listing of Claims** that begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.

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